# High Current Surface Mount PNP Silicon Switching Transistor for Load Management in Portable Applications

#### **Features**

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

## **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V <sub>CEO</sub>	-30	Vdc
Collector - Base Voltage	V <sub>CBO</sub>	<b>-</b> 50	Vdc
Emitter - Base Voltage	V <sub>EBO</sub>	-5.0	Vdc
Collector Current – Continuous	I <sub>C</sub>	-1.0	Adc
Collector Current – Peak	I <sub>CM</sub>	-2.0	Α

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	310 2.5	mW mW/°C
Thermal Resistance Junction-to-Ambient (Note 1)	$R_{\theta JA}$	403	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	710 5.7	mW mW/°C
Thermal Resistance Junction-to-Ambient (Note 2)	$R_{\theta JA}$	176	°C/W
Total Device Dissipation (Ref. Figure 8) (Single Pulse < 10 sec.)	P <sub>Dsingle</sub>	575	mW
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. FR-4 @ Minimum Pad
- 2. FR-4 @ 1.0 X 1.0 inch Pad



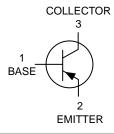
## ON Semiconductor®

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# 30 VOLTS, 2.0 AMPS PNP TRANSISTORS



SOT-23 (TO-236) CASE 318 STYLE 6



#### **MARKING DIAGRAM**



G3 = Device Code

M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)
\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBT589LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
NSVMMBT589LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

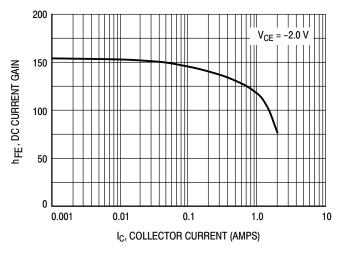
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage $(I_C = -10 \text{ mAdc}, I_B = 0)$	V <sub>(BR)</sub> CEO	 -30	_	Vdc	
Collector – Base Breakdown Voltage $(I_C = -0.1 \text{ mAdc}, I_E = 0)$	V <sub>(BR)</sub> CBO	-50	-	Vdc	
Emitter – Base Breakdown Voltage (I <sub>E</sub> = -0.1 mAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	-5.0	-	Vdc	
Collector Cutoff Current (V <sub>CB</sub> = -30 Vdc, I <sub>E</sub> = 0)	Ісво	_	-0.1	μAdc	
Collector–Emitter Cutoff Current (V <sub>CES</sub> = -30 Vdc)	I <sub>CES</sub>	_	-0.1	μAdc	
Emitter Cutoff Current (V <sub>EB</sub> = -4.0 Vdc)	I <sub>EBO</sub>	_	-0.1	μAdc	
ON CHARACTERISTICS					
DC Current Gain (Note 3) (Figure 1) $ \begin{aligned} &(I_C = -1.0 \text{ mA, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -500 \text{ mA, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -1.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = 2.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \end{aligned} $	h <sub>FE</sub>	100 100 80 40	- 300 - -	-	
Collector – Emitter Saturation Voltage (Note 3) (Figure 3) $ \begin{pmatrix} I_C = -0.5 \text{ A}, I_B = -0.05 \text{ A} \end{pmatrix} $ $ \begin{pmatrix} I_C = -1.0 \text{ A}, I_B = 0.1 \text{ A} \end{pmatrix} $ $ \begin{pmatrix} I_C = -2.0 \text{ A}, I_B = -0.2 \text{ A} \end{pmatrix} $	V <sub>CE(sat)</sub>	- - -	-0.25 -0.30 -0.65	V	
Base – Emitter Saturation Voltage (Note 3) (Figure 2) $(I_C = -1.0 \text{ A}, I_B = -0.1 \text{ A})$	V <sub>BE(sat)</sub>	_	-1.2	V	
Base – Emitter Turn–on Voltage (Note 3) (I <sub>C</sub> = -1.0 A, V <sub>CE</sub> = -2.0 V)	V <sub>BE(on)</sub>	-	-1.1	V	
Cutoff Frequency ( $I_C = -100 \text{ mA}$ , $V_{CE} = -5.0 \text{ V}$ , $f = 100 \text{ MHz}$ )	f <sub>T</sub>	100	_	MHz	
Output Capacitance (f = 1.0 MHz)	Cobo	_	15	pF	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

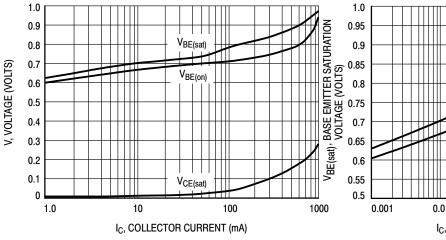
3. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%



230  $V_{CE} = -1.0 V$ 210 125°C 190 hFE, DC CURRENT GAIN 170 150 25°C 130 110 90 -55°C 70 50 1.0 10 100 1000 IC, COLLECTOR CURRENT (mA)

Figure 1. DC Current Gain versus **Collector Current** 

Figure 2. DC Current Gain versus **Collector Current** 



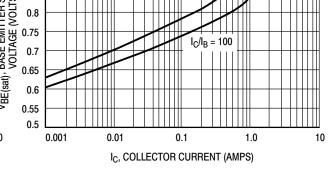
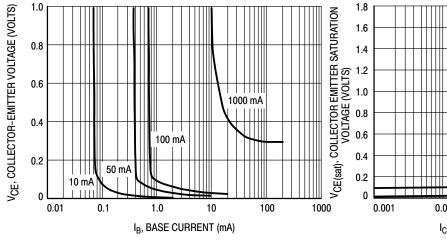


Figure 3. "On" Voltages

Figure 4. Base Emitter Saturation Voltage versus Collector Current

 $I_C/I_B = 100$ 



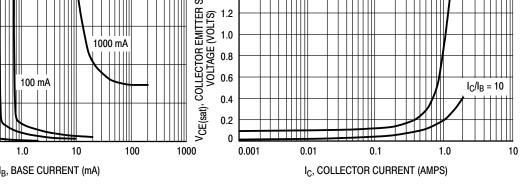


Figure 5. Collector Emitter Saturation Voltage versus Collector Current

Figure 6. Collector Emitter Saturation Voltage versus Collector Current

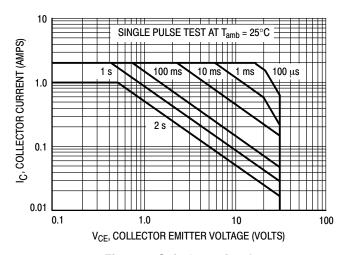


Figure 7. Safe Operating Area

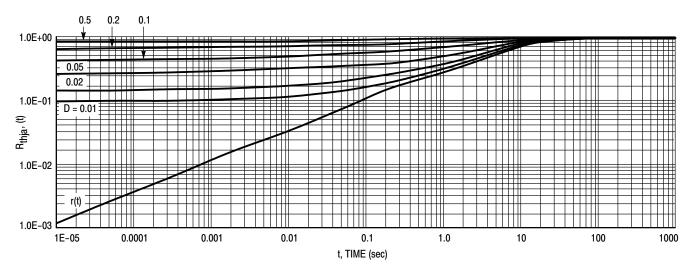
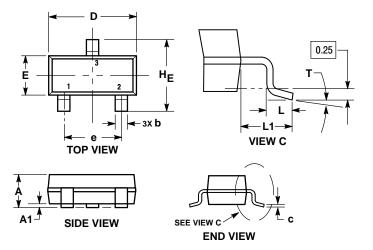


Figure 8. Normalized Thermal Response

#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR** 



#### NOTES

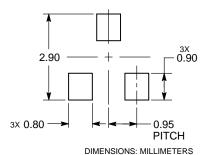
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
T	0°		10°	0°		10°

#### STYLE 6:

- PIN 1. BASE 2. EMITTER
  - COLLECTOR

### **RECOMMENDED** SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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